

Product Change Notification / RMES-18HGMY370

Date:

19-Mar-2021

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3296.003 Final Notice: Qualification of gold (Au) bond wire for selected Atmel ATTINY88xx, ATTINY48xx, ATMEGA88PAxx, ATMEGA168PAx, ATMEGA8Axx, ATMEGA328x and ATMEGA48xx device families available in 32L TQFP (7x7x1mm) package

Affected CPNs:

RMES-18HGMY370_Affected_CPN_03192021.pdf RMES-18HGMY370_Affected_CPN_03192021.csv

Notification Text:

PCN Status: Final Notice

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of gold (Au) bond wire for selected Atmel ATTINY88xx, ATTINY48xx, ATMEGA88PAxx, ATMEGA168PAx, ATMEGA8Axx, ATMEGA328x and ATMEGA48xx device families available in 32L TQFP (7x7x1mm) package.

Pre and Post Change Summary:

| Pre Change Post Cha |
|---------------------|
|---------------------|

| Assembly Site | Microchip Technology Thailand (HQ (MTAI) | Microchip Technology Thailand (HQ (MTAI) | |
|---------------------------|---|---|--|
| Wire material | CuPdAu | CuPdAu CuPdAu or Au | |
| Die attach material | 3280 | 3280 | |
| Molding compound material | G700HA | G700HA | |
| Lead frame material | C7025 | C7025 | |

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on-time delivery performance by qualifying gold (Au) bond wire.

Change Implementation Status: In Progress

Estimated First Ship Date: March 31, 2021 (date code: 2114)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

| | March 2021 | | | | |
|-------------------------------------|------------|----|----|----|----|
| Workweek | 10 | 11 | 12 | 13 | 14 |
| Qual Report Availability | | | Х | | |
| Final PCN Issue Date | | | Х | | |
| Estimated Implementation Date | | | | | Х |

Method to Identify Change: Traceability code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: March 19, 2021: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on March 31, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_RMES-18HGMY370_Qual Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. RMES-18HGMY370 - CCB 3296.003 Final Notice: Qualification of gold (Au) bond wire for selected Atmel ATTINY88xx, ATTINY48xx, ATMEGA88PAxx, ATMEGA168PAx, ATMEGA8Axx, ATMEGA328x and ATMEGA48xx device families available in 32L TQFP (7x7x1mm) package

Affected Catalog Part Numbers (CPN)

ATTINY88-AU ATTINY88-AUR ATTINY48-AU ATTINY48-AUR ATMEGA88PA-AU ATMEGA88PA-AUR ATMEGA168PA-AU ATMEGA168PA-AUR ATMEGA8A-AU ATMEGA8A-AU-HCM ATMEGA8A-AUR ATMEGA328-AU ATMEGA328P-AU ATMEGA328-AUR ATMEGA328P-AUR ATMEGA48A-AU ATMEGA48PA-AU ATMEGA48A-AUR ATMEGA48PA-AUR